

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2891823

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	CHANGE OF NAME
CONVEYING PARTY DATA	
Name	Execution Date
LG SEMICON CO., LTD.	06/10/2014
RECEIVING PARTY DATA	
Name:	SK HYNIX INC.
Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB, ICHEON-SI, GYEONGGI-DO
City:	ICHEON-SI
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	08769059
CORRESPONDENCE DATA	
Fax Number:	(202)315-3758
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2024290020
Email:	pto@nsiplaw.com
Correspondent Name:	NSIP LAW
Address Line 1:	NSIP LAW
Address Line 2:	1120 CONNECTICUT AVE, NW, SUITE 304
Address Line 4:	WASHINGTON, D.C. 20036
NAME OF SUBMITTER:	LOREN H. TUNG
SIGNATURE:	/Loren H. Tung/
DATE SIGNED:	06/10/2014
Total Attachments: 1	
source=MISC20140311_08769059_ChangeofNameExecuted#page1.tif	

CHANGE OF NAME

Please change the name for the following:

LG SEMICON CO., LTD., a Republic of Korea corporation,

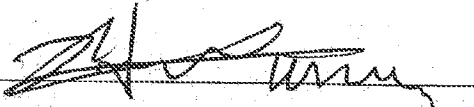
to:

SK HYNIX INC., a Republic of Korea corporation having principal executive office(s) or place of business at: 2091, GYEONGCHUNG-DAERO, BUBAL-EUB, ICHEON-SI, GYEONGGI-DO, REPUBLIC OF KOREA; and

its successors and assigns (collectively hereinafter called "the Assignee"), with respect to the entire right, title and interest throughout the world in the inventions and improvements which are subject of U.S. Patent Application Number 08/769,059, filed December 18, 1996, at the U.S. Patent & Trademark Office, with title APPARATUS FOR CLEANSING SEMICONDUCTOR WAFER; this Change of Name includes said applications, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said applications under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes.

IN TESTIMONY/WITNESS Whereof, undersigned Assignee intending to be legally bound, has hereto affixed its signature by its duly authorized representative.

This 10 day of June, 2014


Signature

HAR YONG-SOO
Printed Name

Director
Title